DATA SHEET 💳

# FUJITSU

## MB1519 ASSP

### DUAL SERIAL INPUT PLL FREQUENCY SYNTHESIZER

#### DUAL SERIAL INPUT PLL FREQUENCY SYNTHESIZER WITH 600MHz PRESCALER

The Fujitsu MB1519 is a 600MHz dual serial input PLL (Phase Locked) frequency synthesizer designed for cellular telephone and cordless telephone applications.

The MB1519 has two PLL circuits on a single chip: one for transmit and the other for reception. Separate power supply pins are provided for the transmit and reception PLL circuits. Transmit PLL contains a low sensitivity charge pump for ease of modulation and reception PLL contains a high sensitivity charge pump for faster lock up time.

600 MHz dual modulus prescalers are on chip and enables a pulse swallow function.

It operates supply voltage of 3.0V typ. and dissipates 11mA typ. of current realized through the use of Fujitsu's unique U-ESBIC Bi-CMOS technology.

- High operating frequency: fin = 600MHz
- Low power supply voltage: V<sub>CC</sub> = 2.7 to 5.5V
- Low power supply current:  $I_{CC} = 11 \text{ mA typ}$ , @3V.
- Wide operating temperature:  $T_A = -40$  to  $85^{\circ}C$
- Two charge pumps Low sensitivity charge pump for transmit High sensitivity charge pump for reception
- Plastic 20-pin dual in line package (Suffix: -P) Plastic 20-pin flat package (Suffix: -PF)

#### ABSOLUTE MAXIMUM RATINGS (see NOTE)

Rating	Symbol	Value	Unit
Dower Supply Voltage	V <sub>CC</sub>	-0.5 to 7.0	V
Power Supply Voltage	VP	V <sub>CC</sub> to 10.0	
Output Voltage	V <sub>OUT</sub>	–0.5 to V <sub>CC</sub> +0.5	V
Output Current	I <sub>OUT</sub>	±10	mA
Storage Temperature	T <sub>STG</sub>	-55 to +125	°C

**NOTE:** Permanent device damage may occur if the above **Absolute Maximum Ratings** are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

#### MB1519



### **BLOCK DESCRIPTIONS**

#### TRANSMIT/RECEPTION BLOCK

- 20-bit latch
- Programmable divider consisting of: Binary 7-bit swallow counter (Divide ratio: 0 to 127) Binary 11-bit programmable counter (Divide ratio: 16 to 2047)
- Phase detector with phase polarity change function
- 600MHz dual modulus prescaler (Divide ratio: 64/65)
- Charge pump

#### **COMMON BLOCK**

- 23-bit shift register
- Programmable divider consisting of: Reference counter (Divide ratio: 512, 1024) (Divide frequency = 25kHz, 12.5kHz (Crystal oscillator frequency = 12.8MHz)
- Crystal oscillator
- fp monitor output selector
- · Latch selector
- Schmitt circuits
- · Analog switches

### **PIN DESCRIPTIONS**

Pin No.	Pin Name	I/O	Descriptions							
1	GND	-	Ground.							
2 3	OSC <sub>IN</sub> OSC- OUT	l O	Oscillator input pin. Oscillator output pin. A crystal is connected between OSC <sub>IN</sub> pin and OSC <sub>OUT</sub> pin.							
4	fin <sub>1</sub>	Ι	Prescaler input pin of transmit section. The connection with VCO should be AC connection.							
5	V <sub>CC1</sub>	-	Power supply voltage input pin of transmit section. When power is OFF, latched data of transmit section is cancelled.							
6	fr	0	Monitor pin for programmable reference divider output.							
7	LD1	0	Lock detect signal output pin of transmit section.      Condition    LD pin output level      Lock    H      Unlock    L							
8	V <sub>P1</sub>	_	Power supply voltage input for charge pump and analog switch of transmit section.							
9	D <sub>O1</sub>	0	Charge pump output pin of transmit section. Phase characteristics of the phase detector can be reversed depending upon FC-bit setting.							
10	BS1	0	Analog switch output pin of transmit section. Usually this pin is high-impedance state. During SW is ON (LE = high), charge pump output is con- nected to this pin.							
11	BS2	0	Analog switch output pin of reception section. Usually this pin is high-impedance state. During SW is ON (LE = high), charge pump output is con- nected to this pin.							
12	D <sub>O2</sub>	0	Charge pump output pin of reception section. Phase characteristics of the phase detector can be reversed depending upon FC-bit setting.							
13	V <sub>P2</sub>	-	Power supply voltage input for charge pump and analog switch of reception section.							
14	LD2	0	Lock detect signal output pin of reception section.							
			Condition LD pin output level							
			Lock H							
			Unlock L							
15	fp	0	Monitor pin for programmable divider output. This pin outputs divided frequency of transmit section or reception section depending upon FP bit set- ting.							
			FP bit Output							
			H Transmit section (fp1)							
			L Reception section (fp2)							

### **PIN DESCRIPTIONS (Continued)**

Pin No.	Pin Name	I/O	Descriptions							
16	V <sub>CC2</sub>	-	Power supply voltage input pin for reception section, programmable reference divider, shift register, and crystal oscillator. When power is OFF, latched data of reception section and reference counter is cancelled.							
17	fin <sub>2</sub>	I	Prescaler input pin of reception section. The connection with VCO should be AC conneciton.							
18	LE	I	Load enable input pin. This pin involves a schmitt trigger circuit. When this pin is high, the data stored in the shift register is transferred into the latch depending on a control data. At this moment, charge pump output signal is output from BS pin since internal analog swith becomes ON.							
19	Data	I	Serial data input pin of 23-bit shift register. This pin involves a schmitt trigger circuit. The stored data in the shift register is transferred to either transmit section or reception section depending upon a control data.							
			Control bit data The destination of data							
			H Latch of transmit section							
			L Latch of reception section							
20	Clock	I	Clock input pin of 23-bit shift register. This pin involves a schmitt trigger circuit. On rising edge of the clock shifts one bit of data into the shift register.							

### **FUNCTIONAL DESCRIPTIONS**

The divide ratio can be calculated using the following equation:

 $f_{VCO} = \{(M \mathrel{x} N) + A\} \mathrel{x} f_{OSC} \div R \quad (A < N)$ 

f<sub>VCO</sub>: Output frequency of external voltage controlled ocillator (VCO)

- M: Preset divide ratio of dual modulus prescaler (64)
- N: Preset divide ratio of binary 11-bit programmable counter (16 to 2047)
- A: Preset divide ratio of binary 7-bit swallow counter ( $0 \le A \le 127$ )

f<sub>OSC</sub>: Reference oscillator frequency

R: Preset divide ratio of reference counter (512 or 1024)

### **FUNCTIONAL DESCRIPTIONS**

#### SERIAL DATA INPUT

Serial data is input using three pins, Data pin, Clock pin, and LE pin. Programmable divider of transmit section and programmable divider of reception section are controlled individually.

Serial data of binary data is input into Data pin.

On rising edge of clock shifts one bit of serial data into the shift register. When load enable signal is high, the data stored in the shift register is transferred to either the latch of transmit section or the latch of reception section depending upon the control bit data setting.

Control data	Destination of serial data
Н	Latch of transmit section
L	Latch of reception section

#### SHIFT REGISTER CONFIGURATION

Control bit

	LSB ∳							Data	a Flow		•									-		MSB ↓
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23
С	R E	F P	D	F	A	A	A	A	A	A	A	N	N	N	N	N	N	N	N	N	N	N
N T	F	P	M Y	С	I	2	3	4	5	6	/	1	Z	3	4	5	6	1	8	9	10	11

N1 to N11 : Divide ratio of the programmable counter setting bit (16 to 2047)

A1 to A7 : Divide ratio of the swallow counter setting bit (0 to 127)

FC : Phase control bit of the phase detector

DMY : Dummy bit (sets to low)

FP : Output of the programmable divider control bit (fp1 or fp2)

REF : Divide ratio of the reference counter setting bit (512 to 1024)

CNT : Control bit

#### SERIAL DATA INPUT TIMING



On rising edge of the clock shifts one bit of the data into the shift register.

#### **BINARY 11-BIT PROGRAMMABLE COUNTER DATA SETTING**

Divide Ratio (N)	N 11	N 10	N 9	N 8	N 7	N 6	N 5	N 4	N 3	N 2	N 1
16	0	0	0	0	0	0	1	0	0	0	0
17	0	0	0	0	0	0	1	0	0	0	1
•	•	•	•	•	•	•	•	•	•	•	•
2047	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 16 is prohibited. Divide ratio (N) range = 16 to 2047

#### **BINARY 7-BIT SWALLOW COUNTER DATA SETTING**

Divide Ratio (A)	A 7	A 6	A 5	A 4	A 3	A 2	A 1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
•	•	•	•	•	•	•	•
127	1	1	1	1	1	1	1

Note: Divide ratio (A) range = 0 to 127

- DMY: DUMMY BIT INPUT This bit is set to low in operation.
- REF : DIVIDE RATIO (R) OF THE REFERENCE COUNTER SETTING BIT H = 512 (fr = 25.0 kHz) L = 1024 (fr = 12.5 kHz)
- FP : OUTPUT OF THE PROGRAMMABLE DIVIDER SETTING BIT
  H = fp pin (15 pin) outputs programmable divider output frequency (fp1) of transmit section.
  L = fp pin (15 pin) outputs programmable divider output frequency (fp2) of reception section.
- FC : PHASE CONTROL BIT OF THE PHASE DETECTOR Output of charge pump is selected by FC pin.

	FC = H	FC = L
fr > fp	Н	L
fr = fp	Z	Z
fr < fp	L	Н
VCO Polarity	(1)	(2)

Note: Z = High-impedance

Depending upon the VCO poratity, FC bit should be set.



### PHASE DETECTOR OUTPUT WAVEFORM



**Note:** • Phase difference detection range =  $-2\pi$  to  $+2\pi$ 

- LD output becomes low when phase difference is  $t_W$  or more. LD output becomes high when phase difference less than  $t_W$  is reperated 3 times or more. (e. g.  $t_W$  = 625 to 1250 ns, foscin = 12.8 MHz)
- Spike apperance depends on the charge pump characteristics. The spike is output to diminish the dead band.
- When fr > fp or fr < fp, spike might not generate depending up the VCO characteristics.

#### ANALOG SWITCH

ON/OFF of the analog switch is controlled by the combination of the control data and LE signal. When the analog switch is ON, BS1, BS2 pin output the charge pump output ( $D_{01}$ ,  $D_{02}$ ). When analog switch is OFF, BS pin is set to high impedance.

	Control data = H Divide ratio of tra	l ansmit section is set	Control data = L Divide ratio of reception section is set			
	LE = H	LE = L	LE = H	LE = L		
Analog switch of transmit section	ON	OFF	OFF	OFF		
Analog switch of reception section	OFF	OFF	ON	OFF		

When a analog switch is inserted between LP1 and LP2, faster lock up time is achieved to reduce LPF time constant during PLL channel switching.



### **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol		Value	Unit	Note		
Farameter	Symbol	Min	Тур	Max	onn		
	V <sub>CC</sub>	2.7	3.0	5.5	V	$V_{CC1} = V_{CC2}$	
Power Supply Voltage	V <sub>P</sub>	V <sub>CC</sub>	-	8.0	V		
Input Voltage	V <sub>IN</sub>	GND	-	V <sub>CC</sub>	V		
Operating Temperature	T <sub>A</sub>	-40	-	+85	°C		

#### HANDLING PRECAUTIONS

- This device should be transported and stored in anti-static containers.
- This is a static-sensitive device; take proper anti-ESD precautions. Ensure that personnel and equipment are properly grounded. Cover workbenches with grounded conductive mats.
- Always turn the power supply off before inserting or removing the device from its socket.
- Protect leads with a conductive sheet when handling or transporting PC boards with devices.

### **ELECTRICAL CHARACTERISTICS**

Deremeter		Symbol	Condition		Value	1	Unit	
Parameter		Symbol	Condition	Min	Тур	Max	Onit	
		I <sub>CC1</sub>	Reception section is active.	-	5.5	8.0		
Power Supply Current*		I <sub>CC2</sub>	Transmit/reception section are active.	-	11.0	16.0	mA	
0	fin	fin		10	-	600		
Operating Frequency**	OSC <sub>IN</sub>	f <sub>OSC</sub>		-	12.8	20	MHz	
	<i>C</i>	\ <i>\</i> {{}_{	$V_{CC}$ = 2.7 to 4.0V, 50 $\Omega$	-8	_	0	ID	
Input Sensitivity	fin	Vfin	$V_{CC}$ = 4.0 to 5.5V, 50 $\Omega$	-4	_	4	dBm	
	OSC <sub>IN</sub>	V <sub>OSC</sub>		0.5	_	-	V <sub>PP</sub>	
High-level Input Voltage	Except fin	V <sub>IH</sub>		V <sub>CC</sub> x0.7+0.4	-	-		
Low-level Input Voltage	and OSC <sub>IN</sub>	VIL		_	_	V <sub>CC</sub> x0.3–0.4	V	
High-level Input Current	Data,	I <sub>IH</sub>		_	1.0	-	μΑ	
Low-level Input Current	Clock LE	IIL		-	-1.0	_		
Input Current	OSC <sub>IN</sub>	I <sub>OSC</sub>		-	±50	-		
High-level Output Voltage	Except D <sub>O</sub>	V <sub>OH</sub>	V <sub>CC</sub> = 3.0V	2.2	_	-		
Low-level Output Voltage	and OSC <sub>OUT</sub>	V <sub>OL</sub>		_	_	0.4	V	
High–impedance Cutoff Current	D <sub>O</sub>	I <sub>OFF</sub>	$V_P = V_{CC}$ to 8.0V $V_{OOP} = GND$ to 8.0V	_	_	1.1	μΑ	
	Except D <sub>O</sub>	I <sub>ОН</sub>		-1.0	_	-		
	and OSC <sub>OUT</sub>	I <sub>OL</sub>		1.0	-	_		
Output Current		I <sub>ОН</sub>	V <sub>P</sub> = 6V	_	-1	_	~ ^	
Output Current	D <sub>O1</sub>	I <sub>OL</sub>	$V_{CC} = 3V$	-	12	_	mA	
	D	I <sub>ОН</sub>	V <sub>P</sub> = 6V	-	-3	-		
	D <sub>O2</sub>	I <sub>OL</sub>	$V_{CC} = 3V$	_	6	_		
Analog Switch ON Resistance	9	R <sub>ON</sub>		-	25	-	Ω	

Notes: \*: fin = 600MHz, OSC<sub>IN</sub> = 12.8MHz, V<sub>CC1</sub> = V<sub>CC2</sub> = 3.0V. The remaining input pins are grounded and output pins are open. \*\*: AC coupling. Minimum operating frequency is measured when a capacitor 1000pF is connected.



### **APPLICATION EXAMPLE**



Note: V<sub>P1</sub>, V<sub>P2</sub> :: C1, C2 ::

: depends on the crystal oscillator.

Clock, Data, LE : involve the schmitt circuit.

When input pins are open, please insert the pull down/up resistor individually to prevent the oscillation. : 12.8MHz

X'tal

### PACKAGE DIMENSIONS



### **PACKAGE DIMENSIONS (Continued)**



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